# **MEMS超音波センサ**

MEMS ultrasonic sensor

# 多角的でより多目的なセンシングへ

Multi Purpose and Dimentional Detection

- ▶ 圧電薄膜 (PZT) を使用したMEMS超音波センサ
- ▶ ミラーデバイス技術の応用により、2D・3D検出が可能
- ▶ チップ厚み0.38mm (トータル厚み0.48mm)
- ▶センサ前後の物体検出および距離測定が可能
- ▶Ultrasonic sensor using thin-film piezoelectric MEMS
- ▶2D and 3D detection with implementing structure of MEMS
- ▶Ultra-thin thickness of 0.38 mm(Total thickness of 0.48 mm)
- Detect objects in front and behind and measure distance

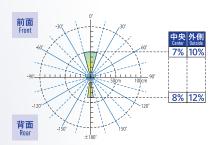
### プロトタイプ(1D)検出領域と距離測定精度

Detection area and accuracy of distance measurement for prototype (1D)

※測定対象物:塩ビパイプ φ90mm ※Measuring Object: PVC pipe ø90mm

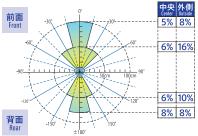
#### 送受信器間距離5cm 5 cm distance between transmitter and receive

送受信器間に高さ3mmの遮蔽板を設置 (受信器から2.5cmの位置) Shielding plate with a height of 3 mm between transmitter and receiver (Located at a distance of 2.5 cm from receiver)



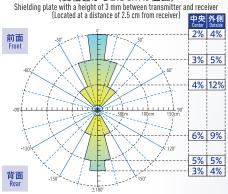
#### 送受信器間距離8cm 8 cm distance between transmitter and receiver

送受信器間に高さ3mmの遮蔽板を設置 (受信器から3.5cmの位置) Shielding plate with a height of 3mm between transmitter and receiver (Located at a distance of 3.5 cm from receiver)



# 送受信器間距離10cm

送受信器間に高さ3mmの遮蔽板を設置 (受信器から2.5cmの位置)



## プロトタイプ構造 Prototype structure

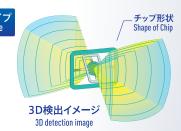




超音波センサ(1D)と ミラーデバイス機構 (XY軸駆動)を ウエハに一体加工

The integrated processing with the ultrasonic sensor "1D" and the mirror device structure "X-Y axis drive" on the wafer. 2**Dタイ**フ 2D type チップ形状 Shape of Chip

2D検出イメージ 2D detection image







ドローンの高さ検知、 障害物検知

Detection of height and obstacles for drone







照明、エアコンの 人感センサ

Human detection sensor for lighting and air conditioner



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